

## Electronic Patent Application Fee Transmittal

Application Number:	10718192
Filing Date:	20-Nov-2003
Title of Invention:	HEAT SPREADER BALL GRID ARRAY (HSBGA) DESIGN FOR LOW-K INTEGRATED CIRCUITS (IC)
First Named Inventor/Applicant Name:	Yian-Liang Kuo
Filer:	Daniel R. McClure/Hui Chin Barnhill
Attorney Docket Number:	TS03-336

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1700</b>